



Welcome to E-XFL.COM

What is "[Embedded - Microcontrollers](#)"?

"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Active
Core Processor	HCS12X
Core Size	16-Bit
Speed	80MHz
Connectivity	CANbus, EBI/EMI, I ² C, IrDA, LINbus, SCI, SPI
Peripherals	LVD, POR, PWM, WDT
Number of I/O	119
Program Memory Size	512KB (512K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.35V ~ 5.5V
Data Converters	A/D 24x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	144-LQFP
Supplier Device Package	144-LQFP (20x20)
Purchase URL	https://www.e-xfl.com/product-detail/nxp-semiconductors/mc9s12xdp512cag

1.2.2 Signal Properties Summary

Table 1-7 summarizes the pin functionality of the MC9S12XDP512. For available modules on other parts of the S12XD, S12XB and S12XA family please refer to [Appendix E Derivative Differences](#).

Table 1-7. Signal Properties Summary (Sheet 1 of 4)

Pin Name Function 1	Pin Name Function 2	Pin Name Function 3	Pin Name Function 4	Pin Name Function 5	Power Supply	Internal Pull Resistor		Description
						CTRL	Reset State	
EXTAL	—	—	—	—	V _{DDPLL}	NA	NA	Oscillator pins
XTAL	—	—	—	—	V _{DDPLL}	NA	NA	
RESET	—	—	—	—	V _{DDR}	PULLUP		External reset
TEST	—	—	—	—	N.A.	RESET pin	DOWN	Test input
VREGEN	—	—	—	—	V _{DDX}	PUCR	Up	Voltage regulator enable Input
XFC	—	—	—	—	V _{DDPLL}	NA	NA	PLL loop filter
BKGD	MODC	—	—	—	V _{DDX}	Always on	Up	Background debug
PAD[23:08]	AN[23:8]	—	—	—	V _{DDA}	PER0/ PER1	Disabled	Port AD I/O, Port AD inputs of ATD1 and analog inputs of ATD1
PAD[07:00]	AN[7:0]	—	—	—	V _{DDA}	PER1	Disabled	Port AD I/O, Port AD inputs of ATD0 and analog inputs of ATD0
PA[7:0]	—	—	—	—	V _{DDR}	PUCR	Disabled	Port A I/O
PB[7:0]	—	—	—	—	V _{DDR}	PUCR	Disabled	Port BI/O
PA[7:0]	ADDR[15:8]	IVD[15:8]	—	—	V _{DDR}	PUCR	Disabled	Port A I/O, address bus, internal visibility data
PB[7:1]	ADDR[7:1]	IVD[7:0]	—	—	V _{DDR}	PUCR	Disabled	Port B I/O, address bus, internal visibility data
PB0	ADDR0	UDS	—	—	V _{DDR}	PUCR	Disabled	Port B I/O, address bus, upper data strobe
PC[7:0]	DATA[15:8]	—	—	—	V _{DDR}	PUCR	Disabled	Port C I/O, data bus
PD[7:0]	DATA[7:0]	—	—	—	V _{DDR}	PUCR	Disabled	Port D I/O, data bus
PE7	ECLKX2	XCLKS	—	—	V _{DDR}	PUCR	Up	Port E I/O, system clock output, clock select
PE6	TAGHI	MODB	—	—	V _{DDR}	While RESET pin is low: down		Port E I/O, tag high, mode input
PE5	RE	MODA	TAGLO	—	V _{DDR}	While RESET pin is low: down		Port E I/O, read enable, mode input, tag low input
PE4	ECLK	—	—	—	V _{DDR}	PUCR	Up	Port E I/O, bus clock output
PE3	LSTRB	LDS	EROMCTL	—	V _{DDR}	PUCR	Up	Port E I/O, low byte data strobe, EROMON control
PE2	R/W	WE	—	—	V _{DDR}	PUCR	Up	Port E I/O, read/write
PE1	IRQ	—	—	—	V _{DDR}	PUCR	Up	Port E Input, maskable interrupt

5.3.2.2 ATD Control Register 1 (ATDCTL1)

Writes to this register will abort current conversion sequence but will not start a new sequence.

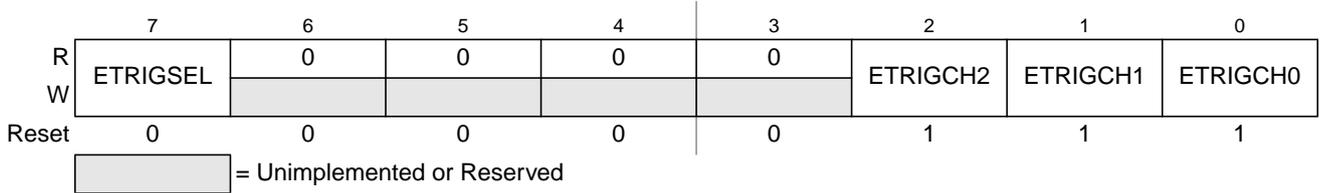


Figure 5-4. ATD Control Register 1 (ATDCTL1)

Read: Anytime

Write: Anytime

Table 5-3. ATDCTL1 Field Descriptions

Field	Description
7 ETRIGSEL	External Trigger Source Select — This bit selects the external trigger source to be either one of the AD channels or one of the ETRIG3–0 inputs. See the device overview chapter for availability and connectivity of ETRIG3–0 inputs. If ETRIG3–0 input option is not available, writing a 1 to ETRISEL only sets the bit but has not effect, that means still one of the AD channels (selected by ETRIGCH2–0) is the source for external trigger. The coding is summarized in Table 5-4 .
2–0 ETRIGCH[2:0]	External Trigger Channel Select — These bits select one of the AD channels or one of the ETRIG3–0 inputs as source for the external trigger. The coding is summarized in Table 5-4 .

Table 5-4. External Trigger Channel Select Coding

ETRIGSEL	ETRIGCH2	ETRIGCH1	ETRIGCH0	External trigger source is
0	0	0	0	AN0
0	0	0	1	AN1
0	0	1	0	AN2
0	0	1	1	AN3
0	1	0	0	AN4
0	1	0	1	AN5
0	1	1	0	AN6
0	1	1	1	AN7
1	0	0	0	ETRIG0 ¹
1	0	0	1	ETRIG1 ¹
1	0	1	0	ETRIG2 ¹
1	0	1	1	ETRIG3 ¹
1	1	X	X	Reserved

¹ Only if ETRIG3–0 input option is available (see device overview chapter), else ETRISEL is ignored, that means external trigger source is still on one of the AD channels selected by ETRIGCH2–0

5.4 Functional Description

The ATD is structured in an analog and a digital sub-block.

5.4.1 Analog Sub-Block

The analog sub-block contains all analog electronics required to perform a single conversion. Separate power supplies V_{DDA} and V_{SSA} allow to isolate noise of other MCU circuitry from the analog sub-block.

5.4.1.1 Sample and Hold Machine

The sample and hold (S/H) machine accepts analog signals from the external surroundings and stores them as capacitor charge on a storage node.

The sample process uses a two stage approach. During the first stage, the sample amplifier is used to quickly charge the storage node. The second stage connects the input directly to the storage node to complete the sample for high accuracy.

When not sampling, the sample and hold machine disables its own clocks. The analog electronics still draw their quiescent current. The power down (ADPU) bit must be set to disable both the digital clocks and the analog power consumption.

The input analog signals are unipolar and must fall within the potential range of V_{SSA} to V_{DDA} .

5.4.1.2 Analog Input Multiplexer

The analog input multiplexer connects one of the 8 external analog input channels to the sample and hold machine.

5.4.1.3 Sample Buffer Amplifier

The sample amplifier is used to buffer the input analog signal so that the storage node can be quickly charged to the sample potential.

5.4.1.4 Analog-to-Digital (A/D) Machine

The A/D Machine performs analog to digital conversions. The resolution is program selectable at either 8 or 10 bits. The A/D machine uses a successive approximation architecture. It functions by comparing the stored analog sample potential with a series of digitally generated analog potentials. By following a binary search algorithm, the A/D machine locates the approximating potential that is nearest to the sampled potential.

When not converting the A/D machine disables its own clocks. The analog electronics still draws quiescent current. The power down (ADPU) bit must be set to disable both the digital clocks and the analog power consumption.

Only analog input signals within the potential range of V_{RL} to V_{RH} (A/D reference potentials) will result in a non-railed digital output codes.

BFINSI

Bit Field Insert and Invert

BFINSI

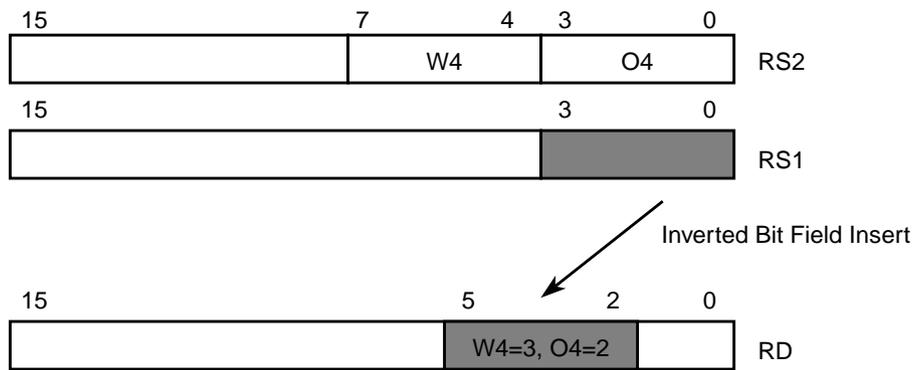
Operation

$$!RS1[w:0] \Rightarrow RD[w+o:0];$$

$$w = (RS2[7:4])$$

$$o = (RS2[3:0])$$

Extracts $w+1$ bits from register RS1 starting at position 0, inverts them and writes into register RD starting at position o . The remaining bits in RD are not affected. If $(o+w) > 15$ the upper bits are ignored. Using R0 as a RS1, this command can be used to set bits.



CCR Effects

N	Z	V	C
Δ	Δ	0	—

- N: Set if bit 15 of the result is set; cleared otherwise.
- Z: Set if the result is \$0000; cleared otherwise.
- V: 0; cleared.
- C: Not affected.

Code and CPU Cycles

Source Form	Address Mode	Machine Code								Cycles		
BFINSI RD, RS1, RS2	TRI	0	1	1	1	0	RD	RS1	RS2	1	1	P

NOTE

The CANRFLG register is held in the reset state¹ when the initialization mode is active (INITRQ = 1 and INITAK = 1). This register is writable again as soon as the initialization mode is exited (INITRQ = 0 and INITAK = 0).

Read: Anytime

Write: Anytime when out of initialization mode, except RSTAT[1:0] and TSTAT[1:0] flags which are read-only; write of 1 clears flag; write of 0 is ignored.

Table 10-9. CANRFLG Register Field Descriptions

Field	Description
7 WUPIF	<p>Wake-Up Interrupt Flag — If the MSCAN detects CAN bus activity while in sleep mode (see Section 10.4.5.4, “MSCAN Sleep Mode,”) and WUPE = 1 in CANTCTL0 (see Section 10.3.2.1, “MSCAN Control Register 0 (CANCTL0)”), the module will set WUPIF. If not masked, a wake-up interrupt is pending while this flag is set.</p> <p>0 No wake-up activity observed while in sleep mode 1 MSCAN detected activity on the CAN bus and requested wake-up</p>
6 CSCIF	<p>CAN Status Change Interrupt Flag — This flag is set when the MSCAN changes its current CAN bus status due to the actual value of the transmit error counter (TEC) and the receive error counter (REC). An additional 4-bit (RSTAT[1:0], TSTAT[1:0]) status register, which is split into separate sections for TEC/REC, informs the system on the actual CAN bus status (see Section 10.3.2.6, “MSCAN Receiver Interrupt Enable Register (CANRIER)”). If not masked, an error interrupt is pending while this flag is set. CSCIF provides a blocking interrupt. That guarantees that the receiver/transmitter status bits (RSTAT/TSTAT) are only updated when no CAN status change interrupt is pending. If the TECs/RECs change their current value after the CSCIF is asserted, which would cause an additional state change in the RSTAT/TSTAT bits, these bits keep their status until the current CSCIF interrupt is cleared again.</p> <p>0 No change in CAN bus status occurred since last interrupt 1 MSCAN changed current CAN bus status</p>
5:4 RSTAT[1:0]	<p>Receiver Status Bits — The values of the error counters control the actual CAN bus status of the MSCAN. As soon as the status change interrupt flag (CSCIF) is set, these bits indicate the appropriate receiver related CAN bus status of the MSCAN. The coding for the bits RSTAT1, RSTAT0 is:</p> <p>00 RxOK: $0 \leq \text{receive error counter} \leq 96$ 01 RxWRN: $96 < \text{receive error counter} \leq 127$ 10 RxERR: $127 < \text{receive error counter}$ 11 Bus-off¹: transmit error counter > 255</p>
3:2 TSTAT[1:0]	<p>Transmitter Status Bits — The values of the error counters control the actual CAN bus status of the MSCAN. As soon as the status change interrupt flag (CSCIF) is set, these bits indicate the appropriate transmitter related CAN bus status of the MSCAN. The coding for the bits TSTAT1, TSTAT0 is:</p> <p>00 TxOK: $0 \leq \text{transmit error counter} \leq 96$ 01 TxWRN: $96 < \text{transmit error counter} \leq 127$ 10 TxERR: $127 < \text{transmit error counter} \leq 255$ 11 Bus-Off: transmit error counter > 255</p>

1. The RSTAT[1:0], TSTAT[1:0] bits are not affected by initialization mode.

10.3.2.17 MSCAN Identifier Acceptance Registers (CANIDAR0-7)

On reception, each message is written into the background receive buffer. The CPU is only signalled to read the message if it passes the criteria in the identifier acceptance and identifier mask registers (accepted); otherwise, the message is overwritten by the next message (dropped).

The acceptance registers of the MSCAN are applied on the IDR0–IDR3 registers (see Section 10.3.3.1, “Identifier Registers (IDR0–IDR3)”) of incoming messages in a bit by bit manner (see Section 10.4.3, “Identifier Acceptance Filter”).

For extended identifiers, all four acceptance and mask registers are applied. For standard identifiers, only the first two (CANIDAR0/1, CANIDMR0/1) are applied.

Module Base + 0x0010 (CANIDAR0)
 0x0011 (CANIDAR1)
 0x0012 (CANIDAR2)
 0x0013 (CANIDAR3)

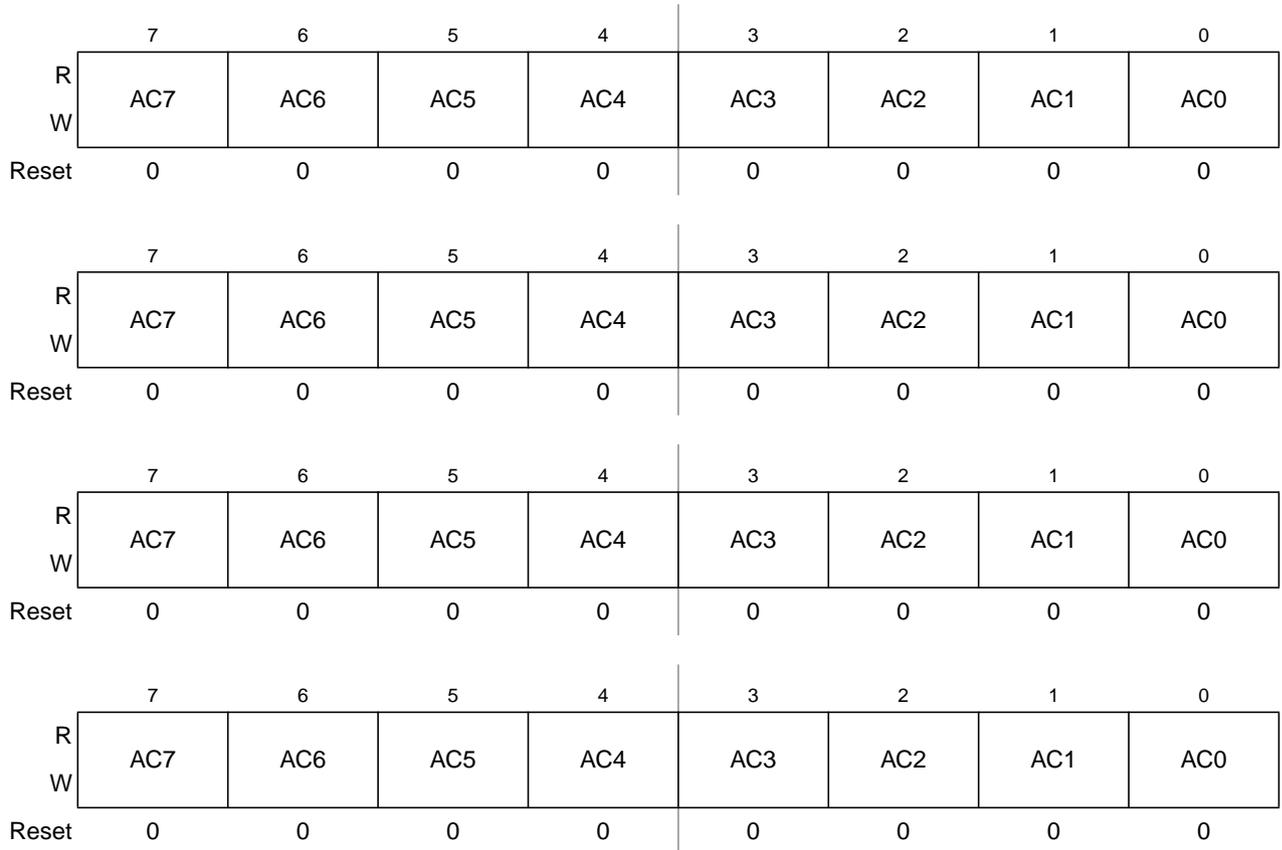


Figure 10-20. MSCAN Identifier Acceptance Registers (First Bank) — CANIDAR0–CANIDAR3

Read: Anytime

Write: Anytime in initialization mode (INITRQ = 1 and INITAK = 1)

12.4.1 Master Mode

The SPI operates in master mode when the MSTR bit is set. Only a master SPI module can initiate transmissions. A transmission begins by writing to the master SPI data register. If the shift register is empty, the byte immediately transfers to the shift register. The byte begins shifting out on the MOSI pin under the control of the serial clock.

- Serial clock

The SPR2, SPR1, and SPR0 baud rate selection bits, in conjunction with the SPPR2, SPPR1, and SPPR0 baud rate preselection bits in the SPI baud rate register, control the baud rate generator and determine the speed of the transmission. The SCK pin is the SPI clock output. Through the SCK pin, the baud rate generator of the master controls the shift register of the slave peripheral.

- MOSI, MISO pin

In master mode, the function of the serial data output pin (MOSI) and the serial data input pin (MISO) is determined by the SPC0 and BIDIROE control bits.

- \overline{SS} pin

If MODFEN and SSOE are set, the \overline{SS} pin is configured as slave select output. The \overline{SS} output becomes low during each transmission and is high when the SPI is in idle state.

If MODFEN is set and SSOE is cleared, the \overline{SS} pin is configured as input for detecting mode fault error. If the \overline{SS} input becomes low this indicates a mode fault error where another master tries to drive the MOSI and SCK lines. In this case, the SPI immediately switches to slave mode, by clearing the MSTR bit and also disables the slave output buffer MISO (or SISO in bidirectional mode). So the result is that all outputs are disabled and SCK, MOSI, and MISO are inputs. If a transmission is in progress when the mode fault occurs, the transmission is aborted and the SPI is forced into idle state.

This mode fault error also sets the mode fault (MODF) flag in the SPI status register (SPISR). If the SPI interrupt enable bit (SPIE) is set when the MODF flag becomes set, then an SPI interrupt sequence is also requested.

When a write to the SPI data register in the master occurs, there is a half SCK-cycle delay. After the delay, SCK is started within the master. The rest of the transfer operation differs slightly, depending on the clock format specified by the SPI clock phase bit, CPHA, in SPI control register 1 (see Section 12.4.3, “Transmission Formats”).

NOTE

A change of the bits CPOL, CPHA, SSOE, LSBFE, MODFEN, SPC0, or BIDIROE with SPC0 set, SPPR2-SPPR0 and SPR2-SPR0 in master mode will abort a transmission in progress and force the SPI into idle state. The remote slave cannot detect this, therefore the master must ensure that the remote slave is returned to idle state.

Table 15-5. Hardware Commands

Command	Opcode (hex)	Data	Description
BACKGROUND	90	None	Enter background mode if firmware is enabled. If enabled, an ACK will be issued when the part enters active background mode.
ACK_ENABLE	D5	None	Enable Handshake. Issues an ACK pulse after the command is executed.
ACK_DISABLE	D6	None	Disable Handshake. This command does not issue an ACK pulse.
READ_BD_BYTE	E4	16-bit address 16-bit data out	Read from memory with standard BDM firmware lookup table in map. Odd address data on low byte; even address data on high byte.
READ_BD_WORD	EC	16-bit address 16-bit data out	Read from memory with standard BDM firmware lookup table in map. Must be aligned access.
READ_BYTE	E0	16-bit address 16-bit data out	Read from memory with standard BDM firmware lookup table out of map. Odd address data on low byte; even address data on high byte.
READ_WORD	E8	16-bit address 16-bit data out	Read from memory with standard BDM firmware lookup table out of map. Must be aligned access.
WRITE_BD_BYTE	C4	16-bit address 16-bit data in	Write to memory with standard BDM firmware lookup table in map. Odd address data on low byte; even address data on high byte.
WRITE_BD_WORD	CC	16-bit address 16-bit data in	Write to memory with standard BDM firmware lookup table in map. Must be aligned access.
WRITE_BYTE	C0	16-bit address 16-bit data in	Write to memory with standard BDM firmware lookup table out of map. Odd address data on low byte; even address data on high byte.
WRITE_WORD	C8	16-bit address 16-bit data in	Write to memory with standard BDM firmware lookup table out of map. Must be aligned access.

NOTE:

If enabled, ACK will occur when data is ready for transmission for all BDM READ commands and will occur after the write is complete for all BDM WRITE commands.

15.4.4 Standard BDM Firmware Commands

Firmware commands are used to access and manipulate CPU resources. The system must be in active BDM to execute standard BDM firmware commands, see [Section 15.4.2, “Enabling and Activating BDM”](#). Normal instruction execution is suspended while the CPU executes the firmware located in the standard BDM firmware lookup table. The hardware command BACKGROUND is the usual way to activate BDM.

As the system enters active BDM, the standard BDM firmware lookup table and BDM registers become visible in the on-chip memory map at 0x7FFF00–0x7FFFFF, and the CPU begins executing the standard BDM firmware. The standard BDM firmware watches for serial commands and executes them as they are received.

The firmware commands are shown in [Table 15-6](#).

Table 17-10. Data Sources when CPU or BDM is Accessing Flash Area

Chip Modes	ROMON	EROMON	DATA SOURCE ¹	Stretch ²
Normal Single Chip	X	X	Internal	N
Special Single Chip				
Emulation Single Chip	X	0	Emulation Memory	N
	X	1	Internal Flash	
Normal Expanded	0	X	External Application	Y
	1	X	Internal Flash	N
Emulation Expanded	0	X	External Application	Y
	1	0	Emulation Memory	N
	1	1	Internal Flash	
Special Test	0	X	External Application	N
	1	X	Internal Flash	

¹ Internal means resources inside the MCU are read/written.
 Internal Flash means Flash resources inside the MCU are read/written.
 Emulation memory means resources inside the emulator are read/written (PRU registers, flash replacement, RAM, EEPROM and register space are always considered internal).
 External application means resources residing outside the MCU are read/written.

² The external access stretch mechanism is part of the EBI module (refer to EBI Block Guide for details).

17.3.2.6 RAM Page Index Register (RPAGE)

Address: 0x0016

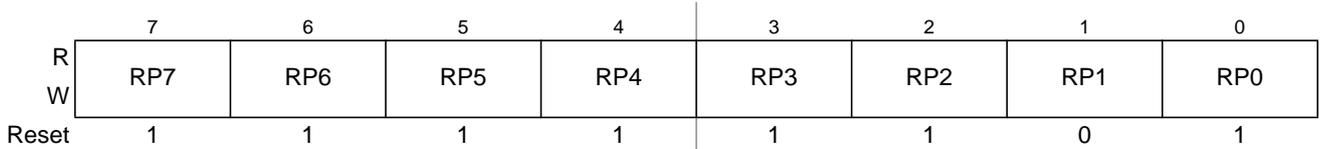


Figure 17-11. RAM Page Index Register (RPAGE)

Read: Anytime

Write: Anytime

The RAM page index register allows accessing up to (1M minus 2K) bytes of RAM in the global memory map by using the eight page index bits to page 4 Kbyte blocks into the RAM page window located in the CPU local memory map from address \$1000 to address \$1FFF (see Figure 1-12).

CAUTION

XGATE write access to this register during an CPU access which makes use of this register could lead to unexpected results.

bit in the DBGCR1 register is cleared, returning the module to the disarmed state0. If tracing is enabled a breakpoint request can occur at the end of the tracing session. If neither tracing nor breakpoints are enabled then when the final state is reached it returns automatically to state0 and the debug module is disarmed.

20.4.5 Trace Buffer Operation

The trace buffer is a 64 lines deep by 64-bits wide RAM array. The S12XDBG module stores trace information in the RAM array in a circular buffer format. The S12XCPU accesses the RAM array through a register window (DBGTBH:DBGTBL) using 16-bit wide word accesses. After each complete 64-bit trace buffer line is read via the S12XCPU, an internal pointer into the RAM is incremented so that the next read will receive fresh information. Data is stored in the format shown in Table 20-39. After each store the counter register bits DBGCRNT[6:0] are incremented. Tracing of S12XCPU activity is disabled when the BDM is active but tracing of XGATE activity is still possible. Reading the trace buffer whilst the BDM is active returns invalid data and the trace buffer pointer is not incremented.

20.4.5.1 Trace Trigger Alignment

Using the TALIGN bits (see Section 20.3.2.3”) it is possible to align the trigger with the end, the middle, or the beginning of a tracing session.

If End or Mid tracing is selected, tracing begins when the ARM bit in DBGCR1 is set and State1 is entered. The transition to Final State if End is selected signals the end of the tracing session. The transition to Final State if Mid is selected signals that another 32 lines will be traced before ending the tracing session. Tracing with Begin-Trigger starts at the opcode of the trigger. Using End or Mid-Trigger or when the tracing is initiated by writing to the TRIG bit whilst configured for Begin-Trigger, tracing starts at the second opcode after writing to DBGCR1 if written in the CPU thread, .

20.4.5.1.1 Storing with Begin-Trigger

Storing with Begin-Trigger, data is not stored in the Trace Buffer until the Final State is entered. Once the trigger condition is met the S12XDBG module will remain armed until 64 lines are stored in the Trace Buffer. If the trigger is at the address of the change-of-flow instruction the change of flow associated with the trigger will be stored in the Trace Buffer. Using Begin-trigger together with tagging, if the tagged instruction is about to be executed then the trace is started. Upon completion of the tracing session the breakpoint is generated, thus the breakpoint does not occur at the tagged instruction boundary.

20.4.5.1.2 Storing with Mid-Trigger

Storing with Mid-Trigger, data is stored in the Trace Buffer as soon as the S12XDBG module is armed. When the trigger condition is met, another 32 lines will be traced before ending the tracing session, irrespective of the number of lines stored before the trigger occurred, then the S12XDBG module is disarmed and no more data is stored. If the trigger is at the address of a change of flow instruction the trigger event is not stored in the Trace Buffer. Using Mid-trigger with tagging, if the tagged instruction is about to be executed then the trace is continued for another 32 lines. Upon tracing completion the breakpoint is generated, thus the breakpoint does not occur at the tagged instruction boundary.

20.4.7.4 Breakpoints Via TAGHI Or TAGLO Pin Taghits

Tagging using the external $\overline{\text{TAGHI}}$ / $\overline{\text{TAGLO}}$ pins always ends the session immediately at the tag hit. It is always end aligned, independent of internal channel trigger alignment configuration.

20.4.7.5 Auxilliary Breakpoint Input

When this signal asserts tracing is terminated and an immediate forced breakpoints are generated, depending on the configuration of DBGBRK bits.

20.4.7.6 S12XDBG Breakpoint Priorities

XGATE software breakpoints have the highest priority. Active tracing sessions are terminated immediately.

If a TRIG trigger occurs after Begin or Mid aligned tracing has already been triggered by a comparator instigated transition to Final State, then TRIG no longer has an effect. When the associated tracing session is complete, the breakpoint occurs. Similarly if a TRIG is followed by a subsequent trigger from a comparator channel whose BRK = 0, it has no effect, since tracing has already started.

If a comparator tag hit occurs simultaneously with an external $\overline{\text{TAGHI}}$ / $\overline{\text{TAGLO}}$ hit, the state sequencer enters state0. TAGHI/TAGLO triggers are always end aligned, to end tracing immediately, independent of the tracing trigger alignment bits TALIGN[1:0].

If a forced and tagged breakpoint coincide, the forced breakpoint occurs too late to prevent the tagged instruction being loaded into the execution unit. Conversely the taghit is too late to prevent the breakpoint request in the DBG module. Thus the S12XCPU suppresses the taghit although the tagged instruction is executed.

Considering the code example below the forced breakpoint is requested when the location COUNTER is accessed. This is signalled to the S12XCPU when the next (tagged) instruction (NOP) is already in the execution stage, thus the tagged instruction is carried out but the tagged breakpoint is suppressed. Reading the PC with BDM READ_PC returns \$C008

```

c000 cf ff 00    START          LDS    #$FF00
c003 a7                NOP
c004 72 70 08          INC    COUNTER ; Forced breakpoint location = COUNTER
c007 a7                NOP          ; Tagged opcode location = MARK
00                BGND
[BDM firmware commands]
c008 20 01          BRA    END ; 1st instruction on return from BDM
    
```

20.4.7.6.1 S12XDBG Breakpoint Priorities And BDM Interfacing

Breakpoint operation is dependent on the state of the S12XBDM module. If the S12XBDM module is active, the S12XCPU is executing out of BDM firmware and S12X breakpoints are disabled. In addition, while executing a BDM TRACE command, tagging into BDM is disabled. If BDM is not active, the breakpoint will give priority to BDM requests over SWI requests if the breakpoint happens to coincide with a SWI instruction in the user's code. On returning from BDM, the SWI from user code gets executed.

Chapter 22

DP512 Port Integration Module (S12XDP512PIMV2)

22.1 Introduction

The S12XD family port integration module (below referred to as PIM) establishes the interface between the peripheral modules including the non-multiplexed external bus interface module (S12X_EBI) and the I/O pins for all ports. It controls the electrical pin properties as well as the signal prioritization and multiplexing on shared pins.

This document covers the description of:

- Port A, B used as address output of the S12X_EBI
- Port C, D used as data I/O of the S12X_EBI
- Port E associated with the S12X_EBI control signals and the IRQ, XIRQ interrupt inputs
- Port K associated with address output and control signals of the S12X_EBI
- Port T connected to the Enhanced Capture Timer (ECT) module
- Port S associated with 2 SCI and 1 SPI modules
- Port M associated with 4 MSCAN modules and 1 SCI module
- Port P connected to the PWM and 2 SPI modules — inputs can be used as an external interrupt source
- Port H associated with 2 SCI modules — inputs can be used as an external interrupt source
- Port J associated with 1 MSCAN, 1 SCI, and 2 IIC modules — inputs can be used as an external interrupt source
- Port AD0 and AD1 associated with one 8-channel and one 16-channel ATD module

Most I/O pins can be configured by register bits to select data direction and drive strength, to enable and select pull-up or pull-down devices. Interrupts can be enabled on specific pins resulting in status flags.

The I/O's of 2 MSCAN and all 3 SPI modules can be routed from their default location to alternative port pins.

NOTE

The implementation of the PIM is device dependent. Therefore some functions are not available on certain derivatives or 112-pin and 80-pin package options.

Table 22-1. Pin Functions and Priorities (Sheet 5 of 7)

Port	Pin Name	Pin Function and Priority	I/O	Description	Pin Function after Reset
P	PP7	PWM7	I/O	Pulse Width Modulator input/output channel 7	GPIO
		SCK2	I/O	Serial Peripheral Interface 2 serial clock pin	
		GPIO/KWP7	I/O	General-purpose I/O with interrupt	
	PP6	PWM6	O	Pulse Width Modulator output channel 6	
		$\overline{SS}2$	I/O	Serial Peripheral Interface 2 slave select output in master mode, input for slave mode or master mode.	
		GPIO/KWP6	I/O	General-purpose I/O with interrupt	
	PP5	PWM5	O	Pulse Width Modulator output channel 5	
		MOSI2	I/O	Serial Peripheral Interface 2 master out/slave in pin	
		GPIO/KWP5	I/O	General-purpose I/O with interrupt	
	PP4	PWM4	O	Pulse Width Modulator output channel 4	
		MISO2	I/O	Serial Peripheral Interface 2 master in/slave out pin	
		GPIO/KWP4	I/O	General-purpose I/O with interrupt	
	PP3	PWM3	O	Pulse Width Modulator output channel 3	
		$\overline{SS}1$	I/O	Serial Peripheral Interface 1 slave select output in master mode, input for slave mode or master mode.	
		GPIO/KWP3	I/O	General-purpose I/O with interrupt	
	PP2	PWM2	O	Pulse Width Modulator output channel 2	
		SCK1	I/O	Serial Peripheral Interface 1 serial clock pin	
		GPIO/KWP2	I/O	General-purpose I/O with interrupt	
	PP1	PWM1	O	Pulse Width Modulator output channel 1	
		MOSI1	I/O	Serial Peripheral Interface 1 master out/slave in pin	
		GPIO/KWP1	I/O	General-purpose I/O with interrupt	
PP0	PWM0	O	Pulse Width Modulator output channel 0		
	MISO1	I/O	Serial Peripheral Interface 1 master in/slave out pin		
	GPIO/KWP0	I/O	General-purpose I/O with interrupt		

22.3.2.43 Port P Polarity Select Register (PPSP)

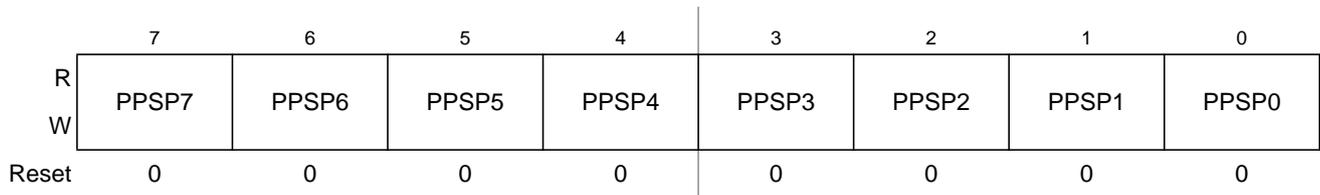


Figure 22-45. Port P Polarity Select Register (PPSP)

Read: Anytime.

Write: Anytime.

This register serves a dual purpose by selecting the polarity of the active interrupt edge as well as selecting a pull-up or pull-down device if enabled.

Table 22-42. PPSP Field Descriptions

Field	Description
7–0 PPSP[7:0]	<p>Polarity Select Port P</p> <p>0 Falling edge on the associated port P pin sets the associated flag bit in the PIFP register. A pull-up device is connected to the associated port P pin, if enabled by the associated bit in register PERP and if the port is used as input.</p> <p>1 Rising edge on the associated port P pin sets the associated flag bit in the PIFP register. A pull-down device is connected to the associated port P pin, if enabled by the associated bit in register PERP and if the port is used as input.</p>

22.3.2.44 Port P Interrupt Enable Register (PIEP)

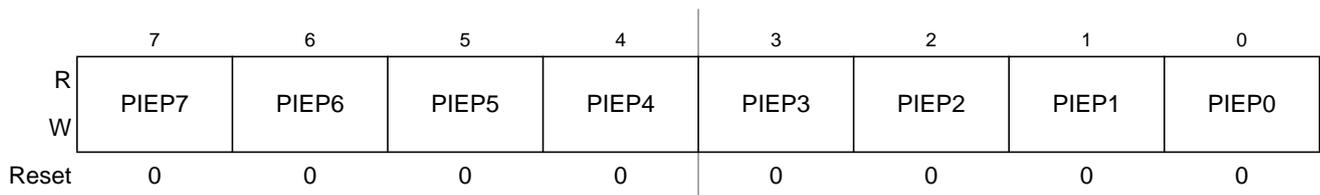


Figure 22-46. Port P Interrupt Enable Register (PIEP)

Read: Anytime.

Write: Anytime.

This register disables or enables on a per-pin basis the edge sensitive external interrupt associated with Port P.

Table 22-43. PIEP Field Descriptions

Field	Description
7–0 PIEP[7:0]	<p>Interrupt Enable Port P</p> <p>0 Interrupt is disabled (interrupt flag masked).</p> <p>1 Interrupt is enabled.</p>

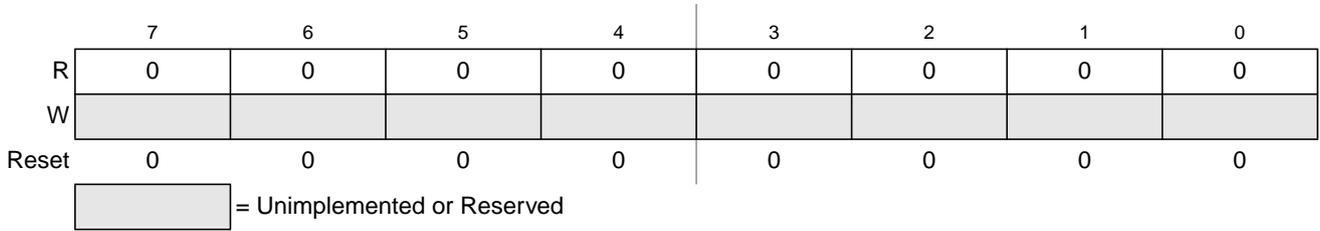


Figure 26-6. RESERVED2

All bits read 0 and are not writable.

26.3.2.4 EEPROM Configuration Register (ECNFG)

The ECNFG register enables the EEPROM interrupts.

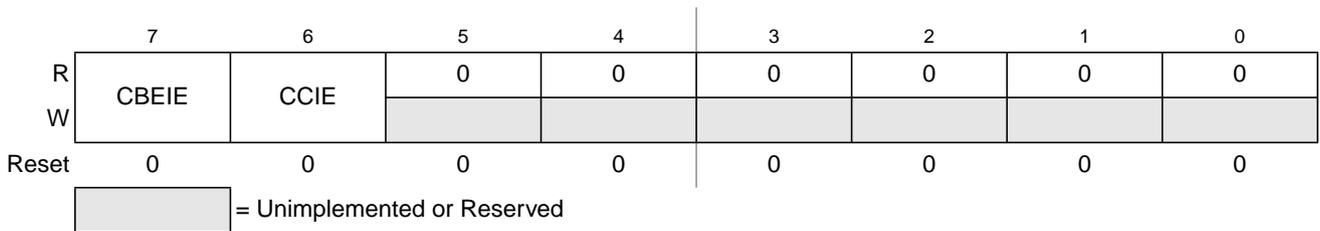


Figure 26-7. EEPROM Configuration Register (ECNFG)

CBEIE and CCIE bits are readable and writable while all remaining bits read 0 and are not writable.

Table 26-4. ECNFG Field Descriptions

Field	Description
7 CBEIE	Command Buffer Empty Interrupt Enable — The CBEIE bit enables an interrupt in case of an empty command buffer in the EEPROM module. 0 Command Buffer Empty interrupt disabled. 1 An interrupt will be requested whenever the CBEIF flag (see Section 26.3.2.6, “EEPROM Status Register (ESTAT)”) is set.
6 CCIE	Command Complete Interrupt Enable — The CCIE bit enables an interrupt in case all commands have been completed in the EEPROM module. 0 Command Complete interrupt disabled. 1 An interrupt will be requested whenever the CCIF flag (see Section 26.3.2.6, “EEPROM Status Register (ESTAT)”) is set.

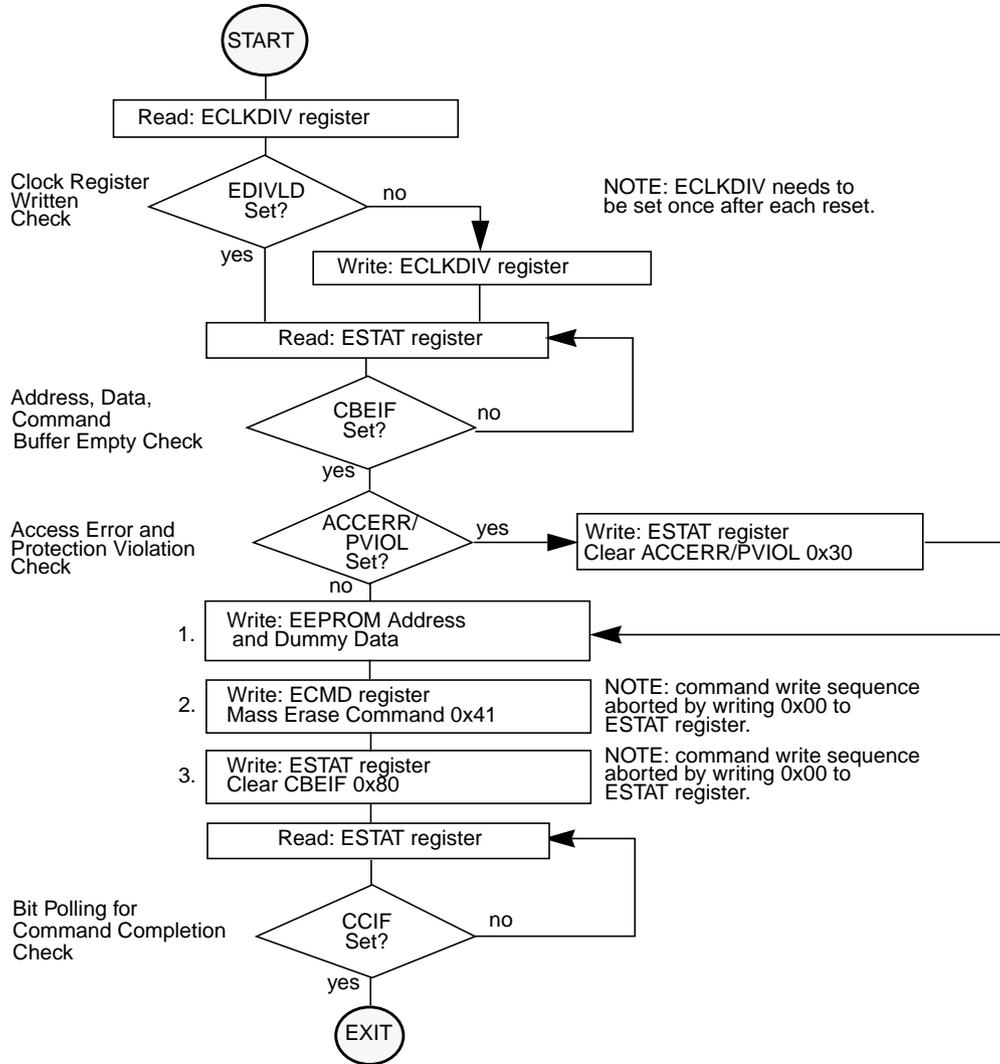
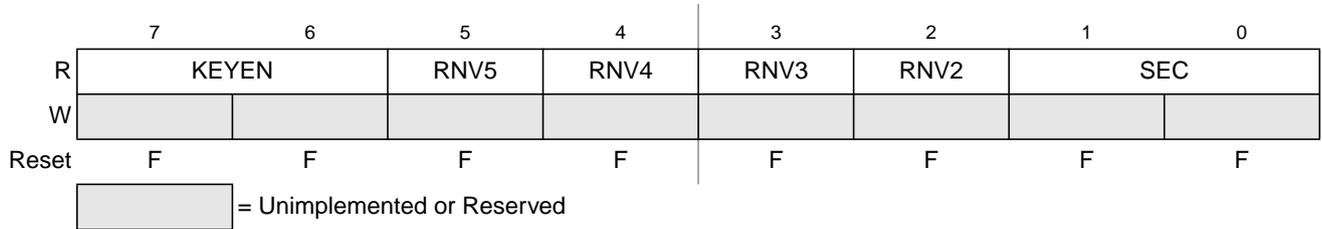


Figure 26-21. Example Mass Erase Command Flow


Figure 27-5. Flash Security Register (FSEC)

All bits in the FSEC register are readable but are not writable.

The FSEC register is loaded from the Flash Configuration Field at address 0x7F_FF0F during the reset sequence, indicated by F in [Figure 27-5](#).

Table 27-4. FSEC Field Descriptions

Field	Description
7-6 KEYEN[1:0]	Backdoor Key Security Enable Bits — The KEYEN[1:0] bits define the enabling of backdoor key access to the Flash module as shown in Table 27-5 .
5-2 RNV[5:2]	Reserved Nonvolatile Bits — The RNV[5:2] bits should remain in the erased state for future enhancements.
1-0 SEC[1:0]	Flash Security Bits — The SEC[1:0] bits define the security state of the MCU as shown in Table 27-6 . If the Flash module is unsecured using backdoor key access, the SEC[1:0] bits are forced to 1:0.

Table 27-5. Flash KEYEN States

KEYEN[1:0]	Status of Backdoor Key Access
00	DISABLED
01 ¹	DISABLED
10	ENABLED
11	DISABLED

1 Preferred KEYEN state to disable Backdoor Key Access.

Table 27-6. Flash Security States

SEC[1:0]	Status of Security
00	SECURED
01 ¹	SECURED
10	UNSECURED
11	SECURED

1 Preferred SEC state to set MCU to secured state.

The security function in the Flash module is described in [Section 27.6, “Flash Module Security”](#).

27.3.2.3 Flash Test Mode Register (FTSTMOD)

The FTSTMOD register is used to control Flash test features.

27.3.2.5.1 Flash Protection Restrictions

The general guideline is that Flash protection can only be added and not removed. Table 27-15 specifies all valid transitions between Flash protection scenarios. Any attempt to write an invalid scenario to the FPROT register will be ignored and the FPROT register will remain unchanged. The contents of the FPROT register reflect the active protection scenario. See the FPHS and FPLS descriptions for additional restrictions.

Table 27-15. Flash Protection Scenario Transitions

From Protection Scenario	To Protection Scenario ¹							
	0	1	2	3	4	5	6	7
0	X	X	X	X				
1		X		X				
2			X	X				
3				X				
4				X	X			
5			X	X	X	X		
6		X		X	X		X	
7	X	X	X	X	X	X	X	X

¹ Allowed transitions marked with X.

27.3.2.6 Flash Status Register (FSTAT)

The FSTAT register defines the operational status of the module.

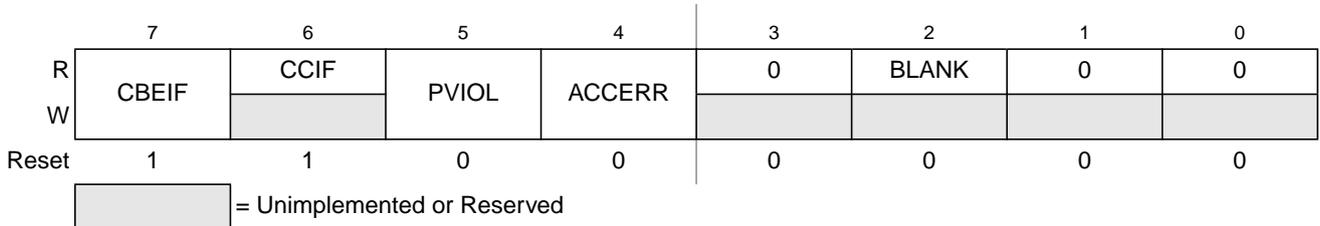
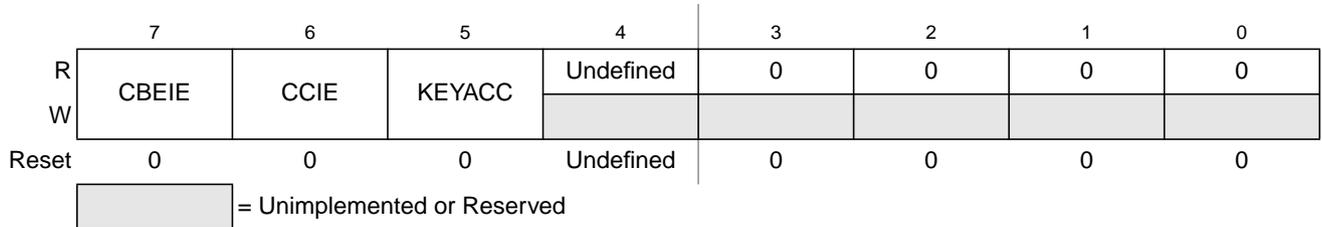
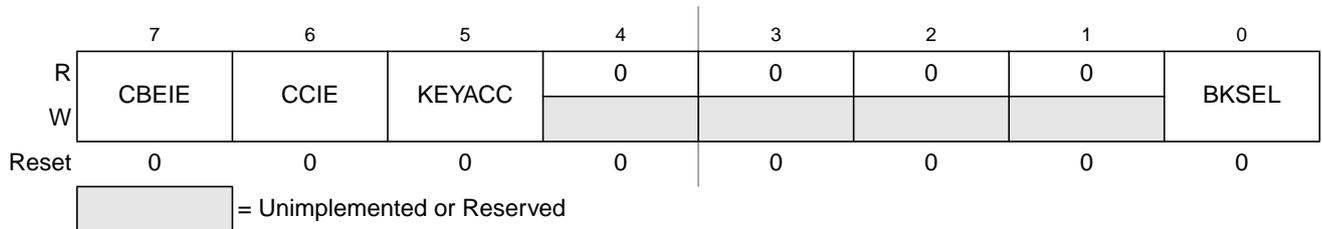


Figure 27-12. Flash Status Register (FSTAT — Normal Mode)



Figure 27-13. Flash Status Register (FSTAT — Special Mode)


Figure 28-8. Flash Configuration Register (FCNFG — Normal Mode)

Figure 28-9. Flash Configuration Register (FCNFG — Special Mode)

CBEIE, CCIE and KEYACC bits are readable and writable while all remaining bits read 0 and are not writable in normal mode. KEYACC is only writable if KEYEN (see [Section 28.3.2.2, “Flash Security Register \(FSEC\)”](#)) is set to the enabled state. BKSEL is readable and writable in special mode to simplify mass erase and erase verify operations. When writing to the FCNFG register in special mode, all unimplemented/ reserved bits must be written to 0.

Table 28-8. FCNFG Field Descriptions

Field	Description
7 CBEIE	Command Buffer Empty Interrupt Enable — The CBEIE bit enables an interrupt in case of an empty command buffer in the Flash module. 0 Command buffer empty interrupt disabled. 1 An interrupt will be requested whenever the CBEIF flag (see Section 28.3.2.6, “Flash Status Register (FSTAT)”) is set.
6 CCIE	Command Complete Interrupt Enable — The CCIE bit enables an interrupt in case all commands have been completed in the Flash module. 0 Command complete interrupt disabled. 1 An interrupt will be requested whenever the CCIF flag (see Section 28.3.2.6, “Flash Status Register (FSTAT)”) is set.
5 KEYACC	Enable Security Key Writing 0 Flash writes are interpreted as the start of a command write sequence. 1 Writes to Flash array are interpreted as keys to open the backdoor. Reads of the Flash array return invalid data.
0 BKSEL	Block Select — The BKSEL bit indicates which register bank is active. 0 Select register bank associated with Flash block 0. 1 Select register bank associated with Flash block 1.

28.3.2.5 Flash Protection Register (FPROT)

The FPROT register defines which Flash sectors are protected against program or erase operations.

A.1.8 Power Dissipation and Thermal Characteristics

Power dissipation and thermal characteristics are closely related. The user must assure that the maximum operating junction temperature is not exceeded. The average chip-junction temperature (T_J) in °C can be obtained from:

$$T_J = T_A + (P_D \cdot \Theta_{JA})$$

T_J = Junction Temperature, [°C]

T_A = Ambient Temperature, [°C]

P_D = Total Chip Power Dissipation, [W]

Θ_{JA} = Package Thermal Resistance, [°C/W]

The total power dissipation can be calculated from:

$$P_D = P_{INT} + P_{IO}$$

P_{INT} = Chip Internal Power Dissipation, [W]

Two cases with internal voltage regulator enabled and disabled must be considered:

1. Internal voltage regulator disabled

$$P_{INT} = I_{DD} \cdot V_{DD} + I_{DDPLL} \cdot V_{DDPLL} + I_{DDA} \cdot V_{DDA}$$

$$P_{IO} = \sum_i R_{DSON} \cdot I_{IO_i}^2$$

P_{IO} is the sum of all output currents on I/O ports associated with V_{DDX} and V_{DDR} .

For R_{DSON} is valid:

$$R_{DSON} = \frac{V_{OL}}{I_{OL}}; \text{for outputs driven low}$$

respectively

$$R_{DSON} = \frac{V_{DD5} - V_{OH}}{I_{OH}}; \text{for outputs driven high}$$

2. Internal voltage regulator enabled

$$P_{INT} = I_{DDR} \cdot V_{DDR} + I_{DDA} \cdot V_{DDA}$$

I_{DDR} is the current shown in Table A-10, and not the overall current flowing into V_{DDR} , which additionally contains the current flowing into the external loads with output high.

$$P_{IO} = \sum_i R_{DSON} \cdot I_{IO_i}^2$$

P_{IO} is the sum of all output currents on I/O ports associated with V_{DDX} and V_{DDR} .